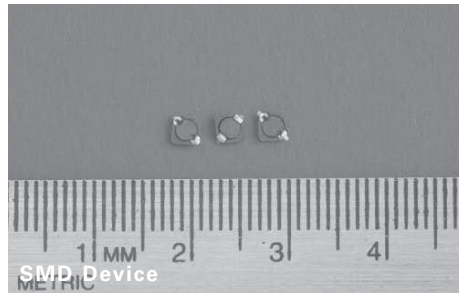


SD3110

Low profile shielded drum core power inductors



Applications

- Mobile phones
- Digital cameras
- Media players
- Small LCD displays
- LED driver and LED flash circuits
- Hard disk drives
- LCD Backlighting

Environmental data

- Storage temperature range (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant

Product features

- 3.1 mm x 3.1 mm x 1.0mm shielded drum core
- Ferrite core material
- Inductance range from 0.5 uH to 220 uH
- Current range from 2.27 A to 0.106 A
- Frequency range up to 1 MHz

RoHS

Discontinued, Effective July 31, 2016 or until inventory is depleted. Please review SD3114 data sheet (4128) as an alternate replacement.

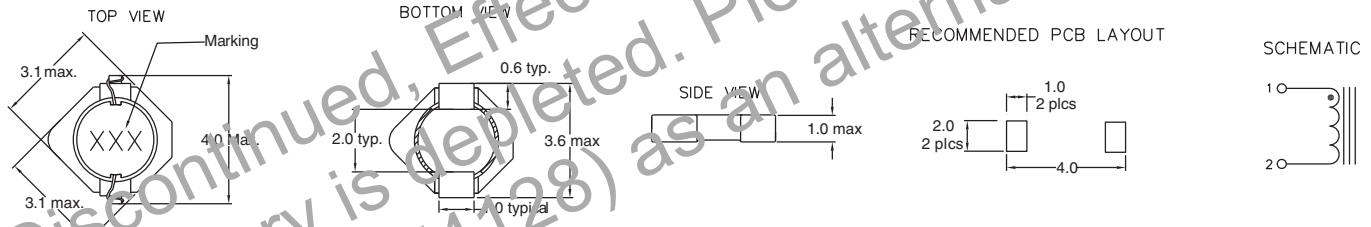
Product specifications

Part Number	Rated Inductance (μH)	OCL (1) (μH)	Part Marking Designator	I _{rms} (2) (A)	I _{sat} (3) (A)	DCR (Ω) typ. @ +20 °C	K-factor (4)
SD3110-R50-R	0.50	0.44+/-30%	A	1.54	2.27	0.0420	216
SD3110-R82-R	0.82	0.82+/-30%	B	1.30	1.67	0.0589	191
SD3110-1R0-R	1.0	1.05+/-30%	C	1.21	1.47	0.0683	169
SD3110-1R5-R	1.5	1.60+/-30%	D	0.99	1.19	0.103	137
SD3110-2R2-R	2.2	2.27+/-30%	E	0.82	1.00	0.149	115
SD3110-3R3-R	3.3	3.48+/-30%	F	0.72	0.81	0.195	93
SD3110-4R7-R	4.7	4.96+/-30%	G	0.59	0.68	0.285	78
SD3110-6R8-R	6.8	6.70+/-30%	H	0.54	0.58	0.346	67
SD3110-8R2-R	8.2	8.01+/-30%	I	0.48	0.53	0.432	61
SD3110-100-R	10.0	10.18+/-30%	J	0.44	0.47	0.505	54
SD3110-150-R	15.0	15.32+/-20%	K	0.36	0.38	0.764	44
SD3110-220-R	22.0	21.49+/-20%	L	0.30	0.32	1.13	37
SD3110-330-R	33.0	32.72+/-20%	M	0.26	0.26	1.50	30
SD3110-470-R	47.0	46.29+/-20%	N	0.22	0.22	2.06	25
SD3110-680-R	68.0	68.04+/-20%	O	0.179	0.182	3.13	21
SD3110-820-R	82.0	82.65+/-20%	P	0.167	0.166	3.57	19
SD3110-101-R	100	101+/-20%	Q	0.146	0.150	4.72	17
SD3110-151-R	150	149+/-20%	R	0.127	0.123	6.16	14
SD3110-221-R	220	219+/-20%	S	0.106	0.120	9.46	12

(1) Open Circuit Inductance Test Parameters: 100 kHz, 0.1 V, 0.0 Adc.
 (2) I_{rms}: DC current for an approximate DT of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.

(3) I_{sat}: Amperes peak for approximately 30% rolloff (@ +20 °C)
 (4) K-factor: Used to determine B_{p-p} for core loss (see graph).
 $B_{p-p} = K \cdot L \cdot \Delta I$, B_{p-p} (mT), K: (K factor from table), L: (Inductance in μH),
 ΔI (Peak to peak ripple current in Amperes).

Dimensions- mm

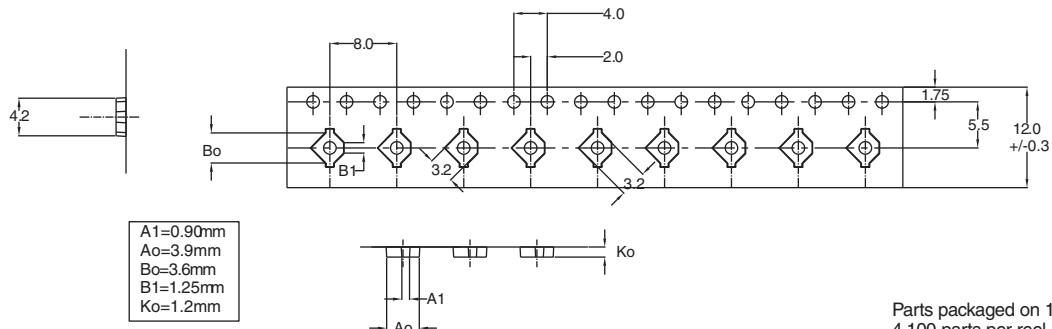


Dimensions are in millimeters.

Part Marking:

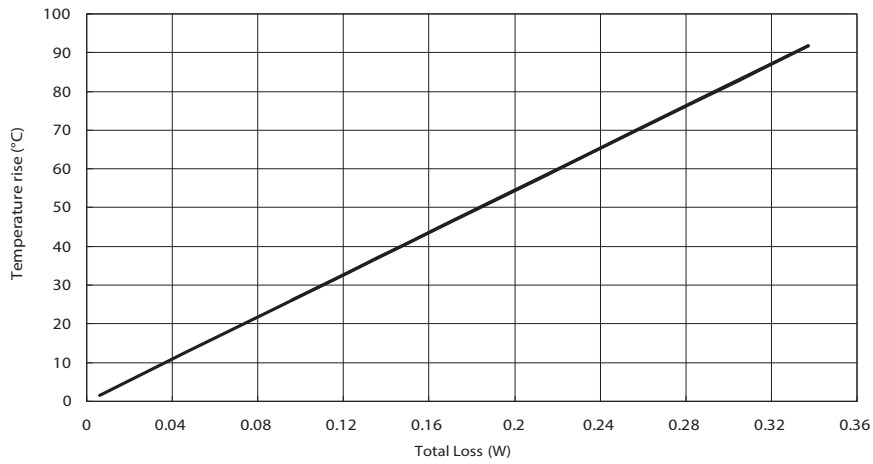
3 Digit Marking: (1st digit: Indicates inductance value per letter in Part Marking Designator); (2nd digit: Bi-weekly production date code); (3rd digit: Last digit of the year produced).
 Do not route trace or vias underneath the inductor

Packaging information- mm

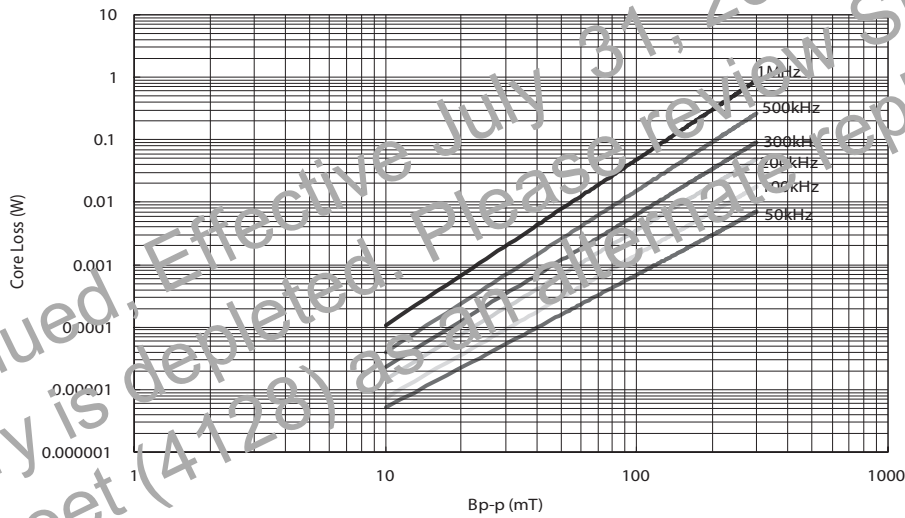


Parts packaged on 13" Diameter reel, 4,100 parts per reel.

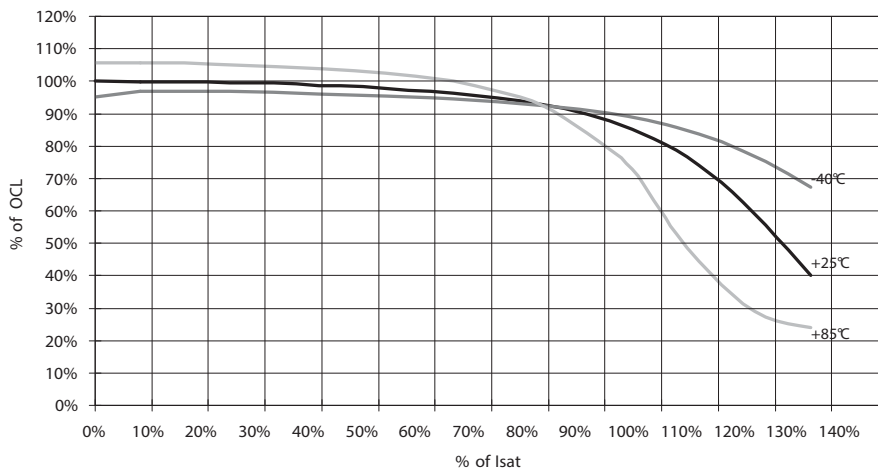
Temperature rise vs total loss loss



Core loss vs Bp-p



Inductance characteristics



Solder Reflow Profile

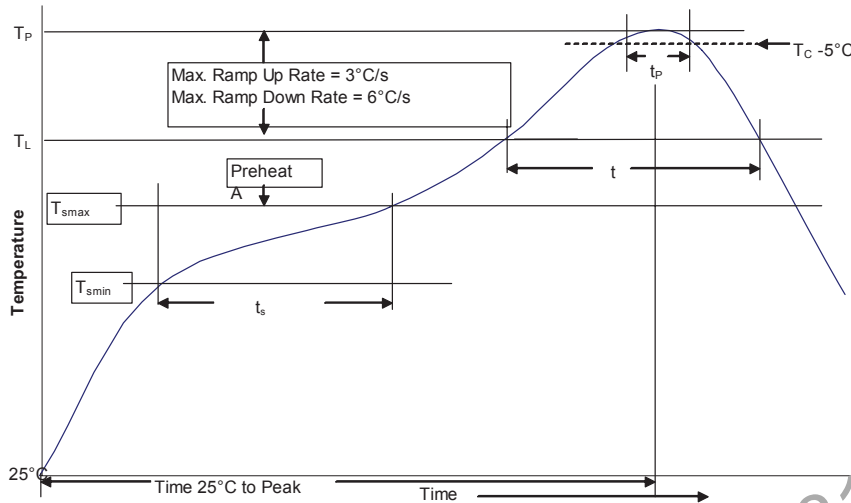


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 \geq 350
<2.5mm	235°C	220°C
\geq 2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	<ul style="list-style-type: none"> Temperature min. (T_{smin}) 100°C Temperature max. (T_{smax}) 150°C Time (T_{smin} to T_{smax}) (t_s) 60-120 Seconds 	<ul style="list-style-type: none"> 150°C 200°C 60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_l)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p ** within 5 °C of the specified classification temperature (T_c))	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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